The US159-DA16600EVZ is an ultra-low power Wi-Fi + Bluetooth™ low energy combo Pmod module that provides both low power Wi-Fi and low power BLE functionality to your device. The DA16600 integrates the low power Wi-Fi DA16200 SoC and the low power Bluetooth LE DA14531 SoC on a single module. Together they deliver long battery life and low power consumption in a convenient form factor. As a single integrated system, standard functions are available such as provisioning Wi-Fi through the BLE connection and Wi-Fi/BLE coexistence.

The US159-DA16600EVZ features a Type 3A Pmod connector, incorporates the DA16600 module, and combines low power Wi-Fi with low power Bluetooth capability in a single module. With its standard connector and software support, the US159-DA16600EVZ is ideal for the Renesas Quick-Connect IoT to rapidly create an IoT system.

Kit Contents
- US159-DA16600EVZ Pmod Board

Features
- DA16600MOD-AAC4WA32 module
  - 3.3V supply voltage
  - Integrated chip antenna
  - Cortex-M4F+ at 30MHz to 160MHz and Cortex M0+ at 16MHz
  - 802.11b/g/n radio PHY, 2.4GHz
  - Bluetooth 5.1 core qualified
  - SoC runs full OS and TCP/IP stack
  - Memory: 256 kB ROM, 512kB RAM, 8kB OTP, 48B retention memory and 32Mb SPI Flash
  - RF regulatory certifications: FCC, IC, CE, KC, TELEC, and SRRC
  - Wi-Fi Alliance certifications: Wi-Fi CERTIFIED b/g/n, WPA, WPA2, and WPA3
- Standardized Type 3A Pmod connector supports an expanded UART interface
- LED (D1) to aid in user software debug
- 10-pin 1.27mm pitch Arm Cortex-Debug connector (J2) for software development and debug support
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1. **Functional Description**

The US159-DA16600EVZ functions as a Wi-Fi and Bluetooth wireless building block to create a custom IoT system solution. This module adds Wi-Fi and Bluetooth connectivity capability to any IoT system that supports Pmod expansion modules. For a full list of available sensor Pmod boards, visit the Quick-Connect IoT web page on the Renesas website.

2. **Setup**

2.1 **Required or Recommended User Equipment**

The following additional lab equipment is recommended for using the board (and is sold separately):

- An MCU board that supports Type 3A Pmod.

2.2 **Software Installation and Usage**

For the latest version of the e2 studio, use the Renesas website, and for the latest connectivity support and details on creating customized IoT system solutions, visit the Quick-Connect IoT site.

The Renesas Flexible Software Package (FSP) is an enhanced software package designed to provide easy-to-use, scalable, high-quality software for embedded system designs using Renesas RA family of Arm Microcontrollers. With the support of a new Arm TrustZone and other advanced security features, FSP provides a quick and versatile way to build secure, connected IoT devices using production-ready drivers, Azure RTOS, FreeRTOS, and other middleware stacks.

The firmware for operating the module is pre-loaded on the US159-DA16600EVZ Pmod module.

<table>
<thead>
<tr>
<th>Firmware</th>
</tr>
</thead>
<tbody>
<tr>
<td>DA16600 v3.2.2.0</td>
</tr>
<tr>
<td>Standard DA16600 SDK</td>
</tr>
</tbody>
</table>

For more details on the application, see the documentation, *Quick-Connect IoT DA16600 Provisioning Demo*.

2.3 **Kit Hardware Connections**

Follow these procedures to set up the kit as shown on [Figure 2](#).

1. Ensure the MCU evaluation kit being used has a Pmod connector set to Type 3A. (For help, refer to the kit hardware manual.)
2. Plug in the US159-DA16600EVZ to the Pmod connector on the MCU evaluation kit, and be careful to align Pin 1 on the module to Pin 1 on the MCU kit.
3. The US159-DA16600EVZ is now ready to be used in the system. Follow the MCU kit instructions for connecting and powering up the evaluation kit.
**Figure 2. Evaluation Kit Details**

- **D1** – LED to aid in user software debug
- **J4** – Install jumper to initiate factory reset
- **J5** – Arm Cortex-debug connector
- **J1** – Pmod connector to MCU board
- **J3** – Serial debug port
- **SW1** – Momentary pushbutton switch to initiate WPS
- **J1** allows for “sniffing” communications on the GTL interface
3. Schematic Diagram

Figure 3. US159-DA16600EVZ Schematic Diagram
### 4. Bill of Materials

<table>
<thead>
<tr>
<th>Qty</th>
<th>Reference Designator</th>
<th>Description</th>
<th>Manufacturer</th>
<th>Manufacturer Part Number</th>
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<tbody>
<tr>
<td>1</td>
<td>B1</td>
<td>Bumper, Cylindrical, 0.375&quot; D, 0.19&quot; HSM</td>
<td>Bumper Specialties</td>
<td>BS35CL01X02RP</td>
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<td>2</td>
<td>C1, C2</td>
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<td>Samsung Electronics-Mechanics</td>
<td>CL05A106MP5JUNP</td>
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<tr>
<td>3</td>
<td>C3, C4, C8</td>
<td>Capacitor, 1µF, 25V, SM 0402, Multilayer Ceramic, X5R, RoHS</td>
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<td>TMK105BJ805KV-F</td>
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<td>Murata</td>
<td>GRM188R61A106KE69D</td>
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<td>C6</td>
<td>Capacitor, 0.1µF, 25V, SM 0402, Multilayer Ceramic, X7R, RoHS</td>
<td>Taiyo Yuden</td>
<td>TMK105BJ8104KVHF</td>
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<td>1</td>
<td>D1</td>
<td>LED, Red, Clear, 0805, SM, RoHS</td>
<td>Wurth Elektronik</td>
<td>150080RS75000</td>
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<td>Sullins</td>
<td>PBC03SAAN</td>
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<td>J2</td>
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<td>Harwin</td>
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<td>J4</td>
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<td>Connector, 2×5 Header, Vertical, 1.27mm Pitch, Pin 7, SM, RoHS</td>
<td>Samtec</td>
<td>FTSH-105-01-L-DV-007-K</td>
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<td>5</td>
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<td>KOA Speer</td>
<td>RK73H1ETTP4701F</td>
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<td>RK73H1ETTP6490F</td>
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<td>SW1</td>
<td>Switch, Pushbutton, Top Actuated, SM, RoHS</td>
<td>C&amp;K Components</td>
<td>PTS810 SJG 250 SMTR LFS</td>
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<td>1</td>
<td>U1</td>
<td>DA16600MOD, WiFi, 802.11b/g/n, Bluetooth LE, Transceiver, WiFi CPU - 256kB ROM, 512kB RAM, 8 kB OTP, 48 kB NV Memory, BLE CPU - 48 kB RAM, 144 kB ROM, 32 kB OTP, 51-SMD Module, RoHS</td>
<td>Dialog Semiconductor</td>
<td>DA16600MOD-AAC4WA32</td>
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<tr>
<td>1</td>
<td>U2</td>
<td>IC, Digital, Buffer, Inverting, Open Drain, SM, SC-70-5, RoHS</td>
<td>Texas Instruments</td>
<td>SN74LVC1G06DCKT</td>
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</table>
4.1 Board Layout

Figure 4. Silkscreen Top

Figure 5. Copper Top

Figure 6. Copper L1 Layer
Figure 7. Copper L2 Layer

Figure 8. Copper Bottom

Figure 9. Silkscreen Bottom
5. Ordering Information

<table>
<thead>
<tr>
<th>Part Number</th>
<th>Description</th>
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<tbody>
<tr>
<td>US159-DA16600EVZ</td>
<td>DA16600 Pmod Board</td>
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6. Revision History

<table>
<thead>
<tr>
<th>Revision</th>
<th>Date</th>
<th>Description</th>
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<td>1.01</td>
<td>Sep 8, 2023</td>
<td>Replaced Figure 1 with updated image</td>
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<tr>
<td>1.00</td>
<td>Jun 27, 2022</td>
<td>Initial release</td>
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